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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 2423.32-2008

**Environmental testing for electric and electronic products - Part
2: Test Methods - Test Ta: Solderability test by the wetting
balance method
(English Translation)**

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1 Scope

This Part of GB/T 2423 outlines Test Ta, solder bath wetting balance method applicable for any shape of component terminations to determine the solderability. It is especially suitable for reference testing and for components that cannot be quantitatively tested by other methods. For surface mounting devices (SMD), IEC 60068-2-69 should be applied if it is suitable.

2 Normative References

The clauses of the following documents become clauses of this Part through the reference in GB/T 2423. In terms of references with a specified date, all subsequent amendments (excluding corrected content) or revisions are not applicable to this

Standard. However, all parties that reach an agreement in accordance with this

Standard are encouraged to explore the possibility of adopting the latest editions of these documents. In terms of references without a specified date, the latest edition is applicable to this Standard.

GB/T 2421-1999 Environmental Testing for Electric and Electronic Products - Part 1:
General and Guidance (idt IEC 60068-1:1988)

GB/T 2423.28-2005 Basic Environmental Testing Procedures for Electric and
Electronic Products - Part 2: Test Methods - Test T: Soldering (IEC 60068-2-20:1979,
IDT)

IEC 61190-1-3:2002 Attachment Materials for Electronic Assembly - Part 1-3:
Requirements for Electronic Grade Solder Alloys and Fluxed and Non-fluxed Solid
Solders for Electronic Soldering Applications

3 Terms and Definitions

For the purposes of this document, the terms and definitions, as defined in GB/T 2421-1999 and GB/T 2423.28-2005, apply.